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(54) POSITIVE PHOTOSENSITIVE THERMOSETTING RESIN COMPOSITION, TRANSFER MATERIAL AND IMAGE-FORMING METHOD

(57)Abstract:

PROBLEM TO BE SOLVED: To provide a positive photosensitive thermosetting resin composition easy to use, because of its superior preservation stability, developable with a low alkaline aqueous solution of about pH 10, having high resolution and giving a film which is superior in transparency heat and solvent resistances and insulating property, after curing.

SOLUTION: The positive photosensitive thermosetting resin composition contains an alkali-soluble resin, obtained by copolymerizing 5-80 mol% polymerizable monomer of general formula I (where R¹ is H or methyl; and X is halogen, hydroxy or a 1-12C alkoxy, aryloxy, alkylcarbonyloxy, arylcarbonyloxy, alkoxycarbonyloxy, aryloxy carbonyloxy, alkylsulfonyloxy or arylsulfonyloxy which may have a substituent) and 5-80 mol% carboxylic acid containing monomer as essential components and 10-120 pts.wt. 1,2-quinonediazido compound based on 100 pts.wt. of the alkali-soluble resin.

